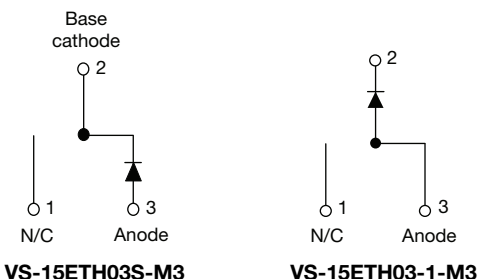
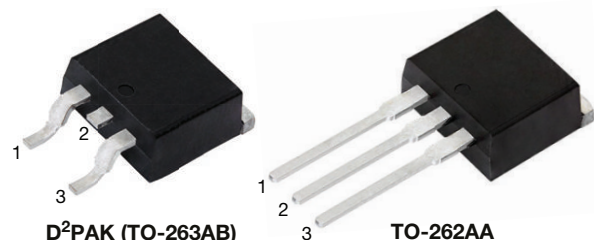


# Hyperfast Rectifier, 15 A FRED Pt®



## FEATURES

- Hyperfast recovery time
- Low forward voltage drop
- Low leakage current
- 175 °C operating junction temperature
- Meets MSL level 1, per J-STD-020, LF maximum peak of 245 °C
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



## DESCRIPTION / APPLICATIONS

Vishay Semiconductors 300 V series are the state of the art hyperfast recovery rectifiers designed with optimized performance of forward voltage drop and hyperfast recovery time.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in the output rectification stage of SMPS, UPS, DC/DC converters as well as freewheeling diodes in low voltage inverters and chopper motor drives.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

## PRIMARY CHARACTERISTICS

$I_{F(AV)}$	15 A
$V_R$	300 V
$V_F$ at $I_F$	0.85 V
$t_{rr}$ (typ.)	40 ns
$T_J$ max.	175 °C
Package	D2PAK (TO-263AB), TO-262AA
Circuit configuration	Single

## ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS
Repetitive peak reverse voltage	$V_{RRM}$		300	V
Average rectified forward current	$I_{F(AV)}$	$T_C = 142\text{ °C}$	15	A
Non-repetitive peak surge current	$I_{FSM}$	$T_J = 25\text{ °C}$	140	
Operating junction and storage temperatures	$T_J, T_{Stg}$		-65 to +175	°C

## ELECTRICAL SPECIFICATIONS ( $T_J = 25\text{ °C}$ unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	$V_{BR}, V_R$	$I_R = 100\text{ }\mu\text{A}$	300	-	-	V
Forward voltage	$V_F$	$I_F = 15\text{ A}$	-	1.05	1.25	
		$I_F = 15\text{ A}, T_J = 125\text{ °C}$	-	0.85	1.00	
Reverse leakage current	$I_R$	$V_R = V_R$ rated	-	0.05	40	$\mu\text{A}$
		$T_J = 125\text{ °C}, V_R = V_R$ rated	-	12	400	
Junction capacitance	$C_T$	$V_R = 300\text{ V}$	-	45	-	pF
Series inductance	$L_S$	Measured lead to lead 5 mm from package body	-	8	-	nH

**DYNAMIC RECOVERY CHARACTERISTICS** ( $T_J = 25\text{ }^{\circ}\text{C}$  unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Reverse recovery time	$t_{rr}$	$I_F = 1.0\text{ A}$ , $di_F/dt = 50\text{ A}/\mu\text{s}$ , $V_R = 30\text{ V}$	-	-	40	ns
		$T_J = 25\text{ }^{\circ}\text{C}$	-	32	-	
		$T_J = 125\text{ }^{\circ}\text{C}$	-	45	-	
Peak recovery current	$I_{RRM}$	$T_J = 25\text{ }^{\circ}\text{C}$	-	2.4	-	A
		$T_J = 125\text{ }^{\circ}\text{C}$	-	6.1	-	
		$I_F = 15\text{ A}$ , $di_F/dt = -200\text{ A}/\mu\text{s}$ , $V_R = 200\text{ V}$	-	-	-	
Reverse recovery charge	$Q_{rr}$	$T_J = 25\text{ }^{\circ}\text{C}$	-	38	-	nC
		$T_J = 125\text{ }^{\circ}\text{C}$	-	137	-	

**THERMAL - MECHANICAL SPECIFICATIONS**

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	$T_J, T_{Stg}$		-65	-	175	$^{\circ}\text{C}$
Thermal resistance, junction to case per leg	$R_{thJC}$		-	1.02	2.0	$^{\circ}\text{C}/\text{W}$
Thermal resistance, junction to ambient per leg	$R_{thJA}$	Typical socket mount	-	-	70	
Thermal resistance, case to heatsink	$R_{thCS}$	Mounting surface, flat, smooth, and greased	-	0.2	-	
Weight			-	2.0	-	g
			-	0.07	-	oz.
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)
Marking device		Case style D <sup>2</sup> PAK (TO-263AB)	15ETH03S			
		Case style TO-262AA	15ETH03-1			

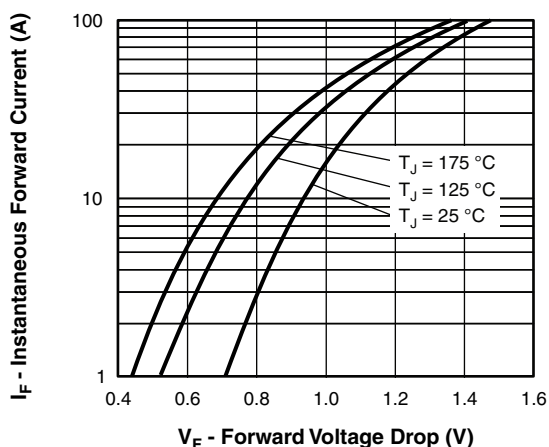


Fig. 1 - Typical Forward Voltage Drop Characteristics

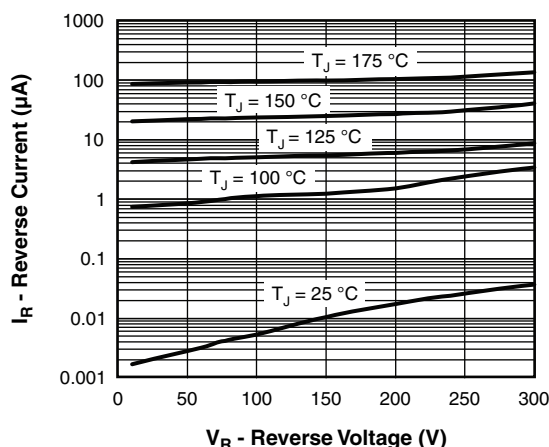


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

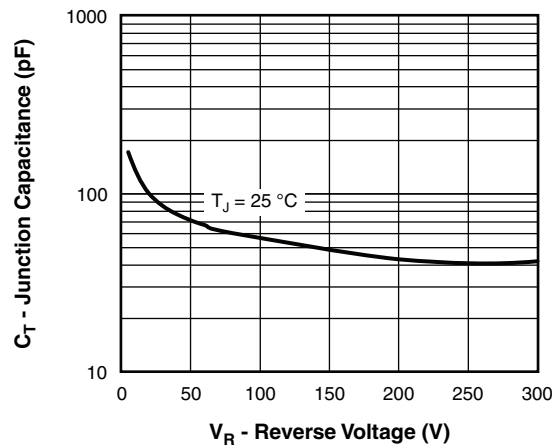


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

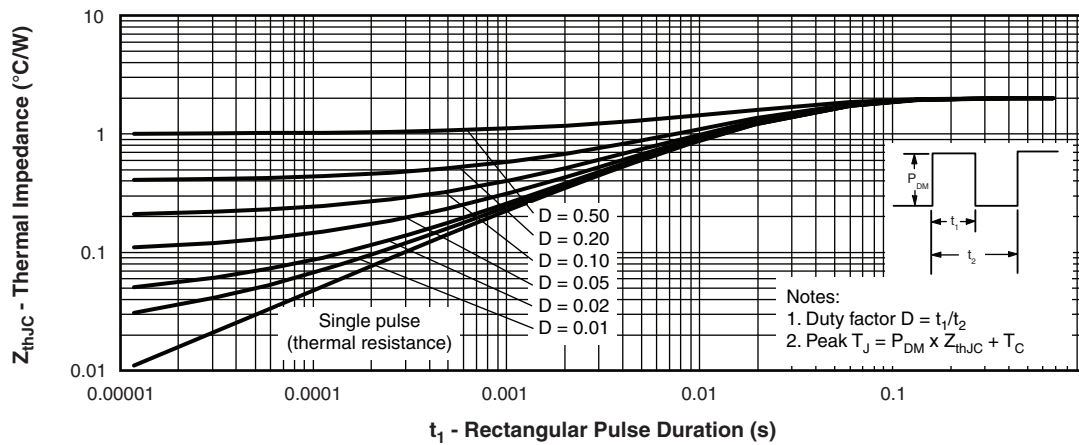
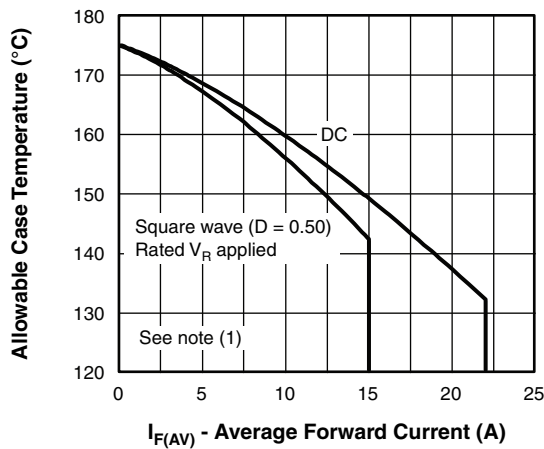

Fig. 4 - Maximum Thermal Impedance  $Z_{thJC}$  Characteristics


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

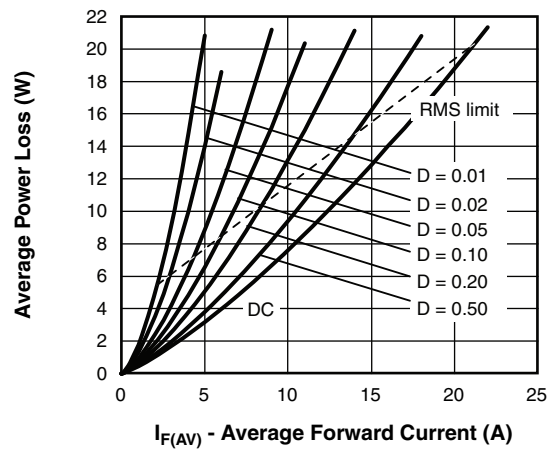
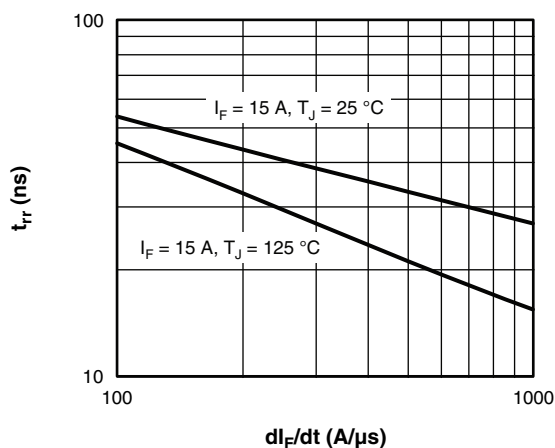
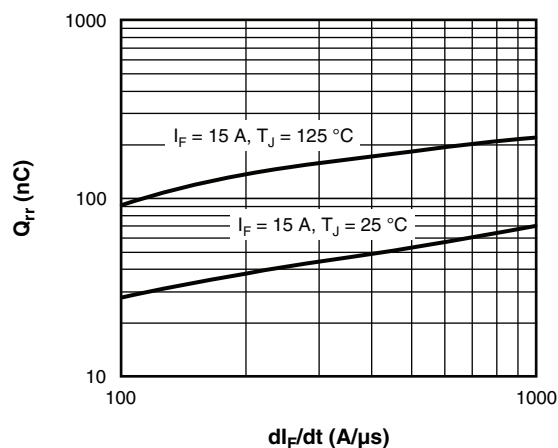


Fig. 6 - Forward Power Loss Characteristics


Fig. 7 - Typical Reverse Recovery Time vs.  $di_F/dt$ 

Fig. 8 - Typical Stored Charge vs.  $di_F/dt$ 
**Note**

- (1) Formula used:  $T_C = T_J - (P_d + P_{d_{REV}}) \times R_{thJC}$ ;  
 $P_d$  = forward power loss =  $I_{F(AV)} \times V_{FM}$  at  $(I_{F(AV)}/D)$  (see fig. 6);  
 $P_{d_{REV}}$  = inverse power loss =  $V_{R1} \times I_R (1 - D)$ ;  $I_R$  at  $V_{R1}$  = rated  $V_R$

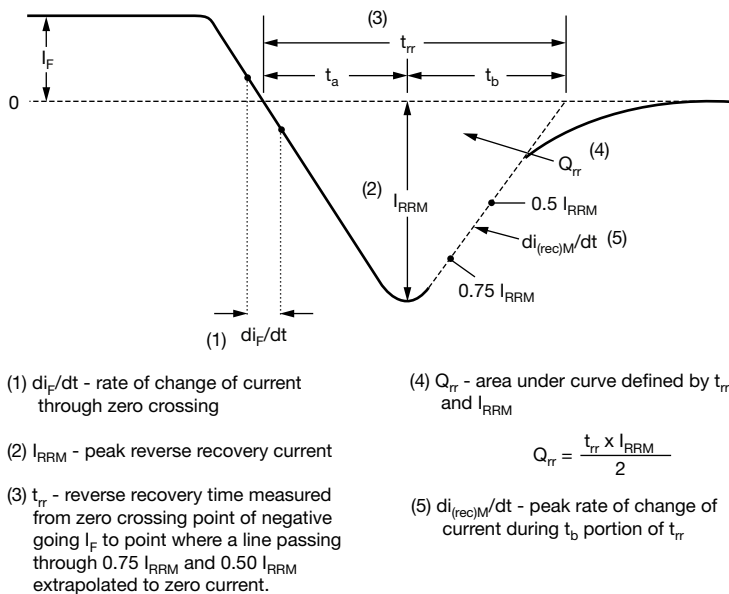


Fig. 9 - Reverse Recovery Waveform and Definitions

## ORDERING INFORMATION TABLE

Device code	<b>VS-</b>	<b>15</b>	<b>E</b>	<b>T</b>	<b>H</b>	<b>03</b>	<b>S</b>	<b>TRL</b>	<b>-M3</b>
	1	2	3	4	5	6	7	8	9

- 1 - Vishay Semiconductors product
- 2 - Current rating (15 A)
- 3 - E = single
- 4 - T = TO-220, D<sup>2</sup>PAK (TO-263AB)
- 5 - H = hyperfast rectifier
- 6 - Voltage rating (03 = 300 V)
- 7 -
  - S = D<sup>2</sup>PAK (TO-263AB)
  - -1 = TO-262AA
- 8 -
  - None = tube (50 pieces)
  - TRL = tape and reel (left oriented, for D<sup>2</sup>PAK (TO-263AB) package)
  - TRR = tape and reel (right oriented, for D<sup>2</sup>PAK (TO-263AB) package)
- 9 - -M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

### ORDERING INFORMATION (Example)

PREFERRED P/N	BASE QUANTITY	PACKAGING DESCRIPTION
VS-15ETH03S-M3	50	Antistatic plastic tubes
VS-15ETH03STRL-M3	800	13" diameter plastic tape and reel
VS-15ETH03STRR-M3	800	13" diameter plastic tape and reel
VS-15ETH03-1-M3	50	Antistatic plastic tubes

## LINKS TO RELATED DOCUMENTS

Dimensions	D <sup>2</sup> PAK (TO-263AB)	<a href="http://www.vishay.com/doc?96164">www.vishay.com/doc?96164</a>
	TO-262AA	<a href="http://www.vishay.com/doc?96165">www.vishay.com/doc?96165</a>
Part marking information	D <sup>2</sup> PAK (TO-263AB)	<a href="http://www.vishay.com/doc?95444">www.vishay.com/doc?95444</a>
	TO-262AA	<a href="http://www.vishay.com/doc?95443">www.vishay.com/doc?95443</a>
Packaging information		<a href="http://www.vishay.com/doc?96424">www.vishay.com/doc?96424</a>
SPICE model		<a href="http://www.vishay.com/doc?96567">www.vishay.com/doc?96567</a>

### D<sup>2</sup>PAK

#### DIMENSIONS in millimeters and inches

Conforms to JEDEC® outline D<sup>2</sup>PAK (SMD-220)



SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	0.160	0.190	
A1	0.00	0.254	0.000	0.010	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
c	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
e	2.54 BSC		0.100 BSC		
H	14.61	15.88	0.575	0.625	
L	1.78	2.79	0.070	0.110	
L1	-	1.65	-	0.066	3
L2	1.27	1.78	0.050	0.070	
L3	0.25 BSC		0.010 BSC		
L4	4.78	5.28	0.188	0.208	

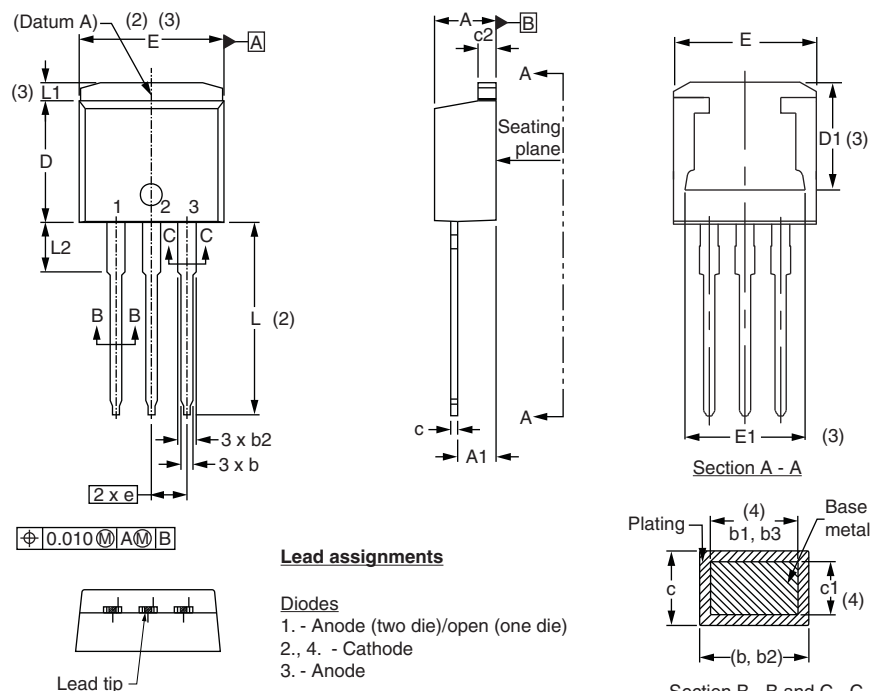
#### Notes

- Dimensioning and tolerancing per ASME Y14.5 M-1994
- Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- Thermal pad contour optional within dimension E, L1, D1 and E1
- Dimension b1 and c1 apply to base metal only
- Datum A and B to be determined at datum plane H
- Controlling dimension: inches
- Outline conforms to JEDEC® outline TO-263AB

### TO-262AA

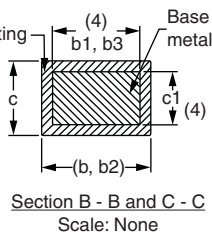
**DIMENSIONS** in millimeters and inches

Modified JEDEC® outline TO-262



#### Lead assignments

- Diodes**  
 1. - Anode (two die)/open (one die)  
 2., 4. - Cathode  
 3. - Anode



SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	0.160	0.190	
A1	2.03	3.02	0.080	0.119	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
c	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
e	2.54 BSC		0.100 BSC		
L	13.46	14.10	0.530	0.555	
L1	-	1.65	-	0.065	3
L2	3.56	3.71	0.140	0.146	

#### Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Controlling dimension: inches
- (6) Outline conform to JEDEC® TO-262 except A1 (max.), b (min., max.), b1 (min.), b2 (max.), c (min.), c1(min.), c2 (max.), D (min.), E (max.), L1 (max.), L2 (min., max.)



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